Retraction

RETRACTED: Liu, X.; Yuan, M. A Global Structural Hypergraph Convolutional Model for Bundle Recommendation. Electronics 2023, 12, 3952

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The Electronics Editorial Office retracts the article “A Global Structural Hypergraph Convolutional Model for Bundle Recommendation“ [1], cited above.

Following publication, the authors contacted the editorial office regarding several significant errors in the experimental methodology and data analysis.

Adhering to our complaint’s procedure, an investigation was conducted by the Editorial Office and Editorial Board that confirmed a number of significant errors in the methodology and data analysis that included:

1. The experimental results represent the best outcome obtained in a single trial, and do not scientifically account for the average of multiple experiments.
2. The results were not recorded according to a uniform standard in the comparative experiments.
3. The experiments were not conducted under the same parameter standards, which resulted in a certain degree of error into the model comparison results.
4. The matrix propagation code does not align with the derivation process. There are discrepancies between the code and the paper.
5. Equation (13) in the paper is not valid.

As a result, the Editorial Office, Editorial Board, and the authors agreed that these errors undermine the validity and credibility of the overall findings presented in the article, and therefore have decided to retract this article as per MDPI's retraction policy (https://www.mdpi.com/ethics#_bookmark30, accessed on 22 February 2024).

This retraction was approved by the Editor-in-Chief of the journal Electronics.

The authors agreed to this retraction.

Reference
1. Liu, X.; Yuan, M. RETRACTED: A Global Structural Hypergraph Convolutional Model for Bundle Recommendation. Electronics 2023, 12, 3952. [CrossRef]

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